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21. The integrated micropotentiometer according to claim 18, wherein the material of said mounting substrate is selected from a group including ceramic, silicon, glass, and metal.

22. The integrated micropotentiometer according to claim 1, wherein said pluralities of first and second serially-connected thermocouples are asymmetrically disposed on either side of said heater element.

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23. The integrated micropotentiometer according to claim 1, wherein said first layer of SiO₂ has a thickness of 20-700 nm, said layer of Si₃N₄ has a thickness of 20-700 nm, and said second layer of SiO₂ has a thickness of 20-700 nm.

24. The integrated micropotentiometer according to claim 1, further comprising a metal housing enclosing said micropotentiometer wherein said metal housing constitutes at least a portion of said return path.

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